



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicants:** Hiroshi Sakai, et al.

**Examiner:** Kevin L. McHenry

**Serial No.:** 10/063,915

**Art Unit:** 1725

**Filed:** May 23, 2002

**Docket:** 15574

**For:** SOLDER PASTE PRINTING METHOD  
AND APPARATUS FOR PRINTING  
SOLDER PASTE ON A BOARD ON  
WHICH WIRING PATTERNS ARE FORMED

**Dated:** February 3, 2005

**Conf. No.:** 4405

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT**

Sir:

In accordance with 37 C.F.R §§1.97 and 1.98, it is requested that the following references, which are also listed on the attached Form PTO-1449, be made of record in the above-identified case.

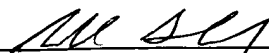
1. European Patent Application Publication No. EP 0 859 540 A1, dated August 19, 1998;
2. Vincent, J.H., et al., "Lead-Free Solders for Electronic Assembly", The GEC Journal of Research (1994), Vol. 11, No. 2, pp. 76-89;

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**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop 313(c), Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on February 3, 2005.

Dated: February 3, 2005

  
Aasheesh V. Shravan

3. Steen, H., "Assessing Lead-Free Solders for Electronics", Electronic Packaging & Production (1994), Vol. 34, No. 12, pp. 32-34, 36;
4. United States Patent No. 5,346,118, issued to Degani et al., dated September 13, 1994;
5. European Patent Application Publication No. EP 0 848 586 A1, dated June 17, 1998; and
6. European Patent Application Publication No. EP 0 867 255 A2, dated September 30, 1998.

The references were cited in a Search Report dated December 8, 2004 received from the European Patent Office. Applicants are submitting copies of the above-cited references, together with a copy of the Search Report. The relevance of the above-identified references has been described in the Search Report.

Inasmuch as this Information Disclosure Statement is being submitted in accordance with the schedule set out in 37 C.F.R. § 1.97(b), no statement or fee is required.

Respectfully submitted,



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<b>INFORMATION DISCLOSURE CITATION</b> (Use several sheets if necessary)				Docket Number (Optional) <b>15574</b>		Application Number <b>10/063,915</b>	
				Applicant(s) <b>Hiroshi Sakai, et al.</b>			
				Filing Date <b>May 23, 2002</b>		Group Art Unit <b>1725</b>	

O I P E J C I S  
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 PATENT & TRADEMARK OFFICE

U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		5,346,118	9/13/1994	Degani et al.			

FOREIGN PATENT DOCUMENTS								
	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
		EP 0 859 540 A1	8/19/1998	EPO				
		EP 0 848 586 A1	6/17/1998	EPO				
		EP 0 867 255 A2	9/30/1998	EPO				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)	
	Vincent, J.H., et al., "Lead-Free Solders for Electronic Assembly", The GEC Journal of Research (1994), Vol. 11, No. 2, pp. 76-89
	Steen, H., "Assessing Lead-Free Solders for Electronics", Electronic Packaging & Production (1994), Vol. 34, No. 12, pp. 32-34, 36

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.